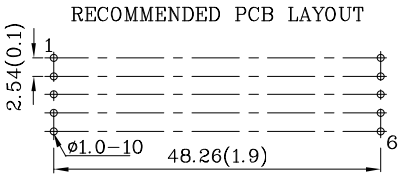
SunLED
www.SunLEDusa.com

Part Number: XDMDK46A

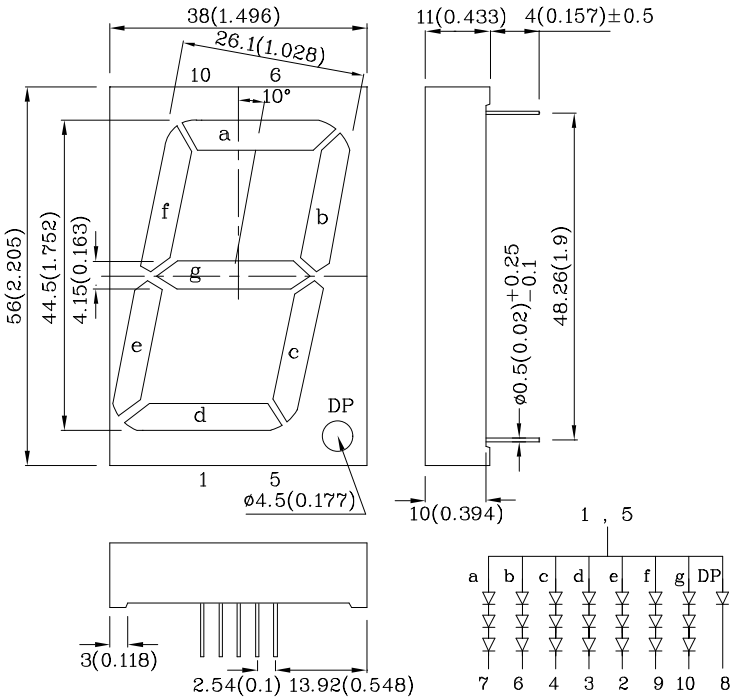
44.5mm (1.75") SINGLE DIGIT NUMERIC DISPLAY

Features

- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



Package Schematics



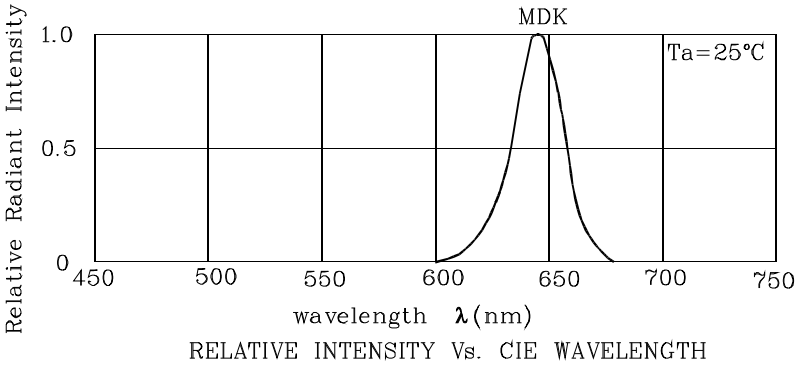
Notes:
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T_A=25°C)		**MDK (AlGaInP)**	**Unit**
Reverse Voltage (Per Chip)	V_R	5	V
Forward Current (Dp)	I_F	30 (30)	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width (Dp)	i_{FS}	185 (185)	mA
Power Dissipation (Per Chip)	P_D	75	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds		

Operating Characteristics (T_A=25°C)		**MDK (AlGaInP)**	**Unit**
Forward Voltage (Typ.) (Dp) (I_F=10mA)	V_F	5.55 (1.85)	V
Forward Voltage (Max.) (Dp) (I_F=10mA)	V_F	7.5 (2.5)	V
Reverse Current (Max.) (Per Chip) (V_R=5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I_F=10mA)	λP	645*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I_F=10mA)	λD	630*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I_F=10mA)	△λ	28	nm
Capacitance (Typ.) (V_F=0V, f=1MHz)	C	35	pF

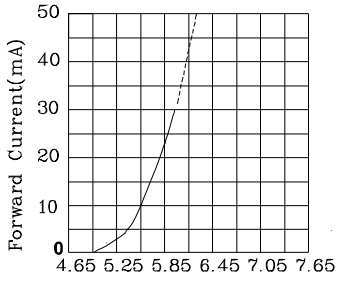
Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I_F=10mA) ucd min.	Luminous Intensity CIE127-2007* (I_F=10mA) ucd typ.	Wavelength CIE127-2007* nm λP	Description
XDMDK46A	Red	AlGaInP	150000 31000*	309990 89990*	645*	Common Anode, Rt.Hand Decimal.

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

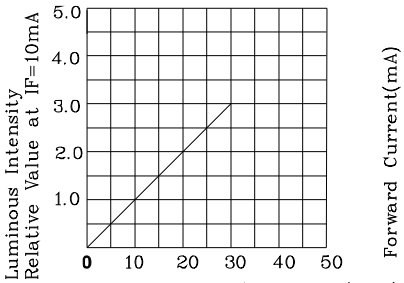


RELATIVE INTENSITY Vs. CIE WAVELENGTH

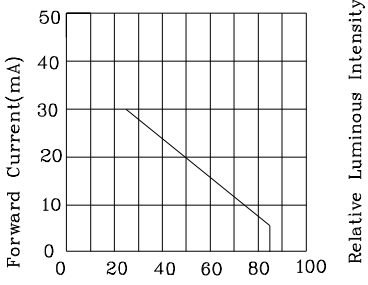
❖ MDK



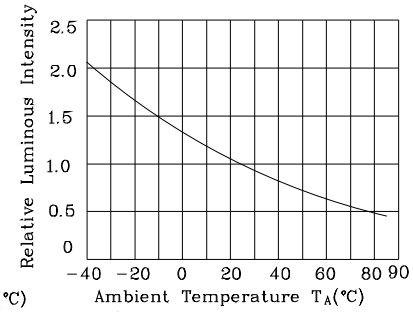
FORWARD CURRENT Vs
FORWARD VOLTAGE



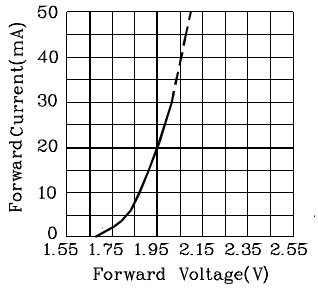
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



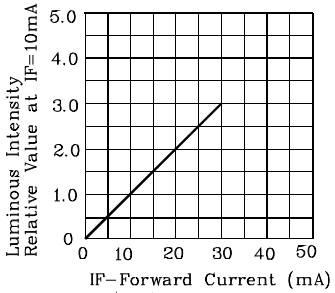
FORWARD CURRENT
DERATING CURVE



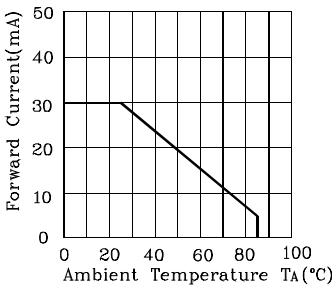
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



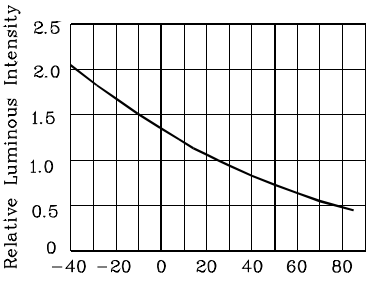
FORWARD CURRENT Vs
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT

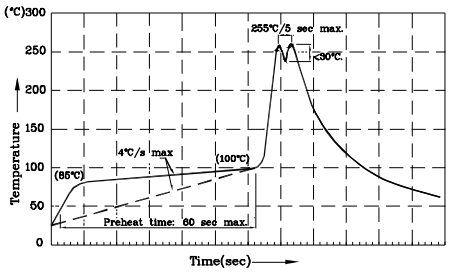


FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

Wave Soldering Profile for Thru–Hole Products (Pb–Free Components)



Notes:
1. Recommend pre–heat temperature of 105℃ or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260℃
2. Peak wave soldering temperature between 245℃ ~ 255℃ for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85℃.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

Remarks:

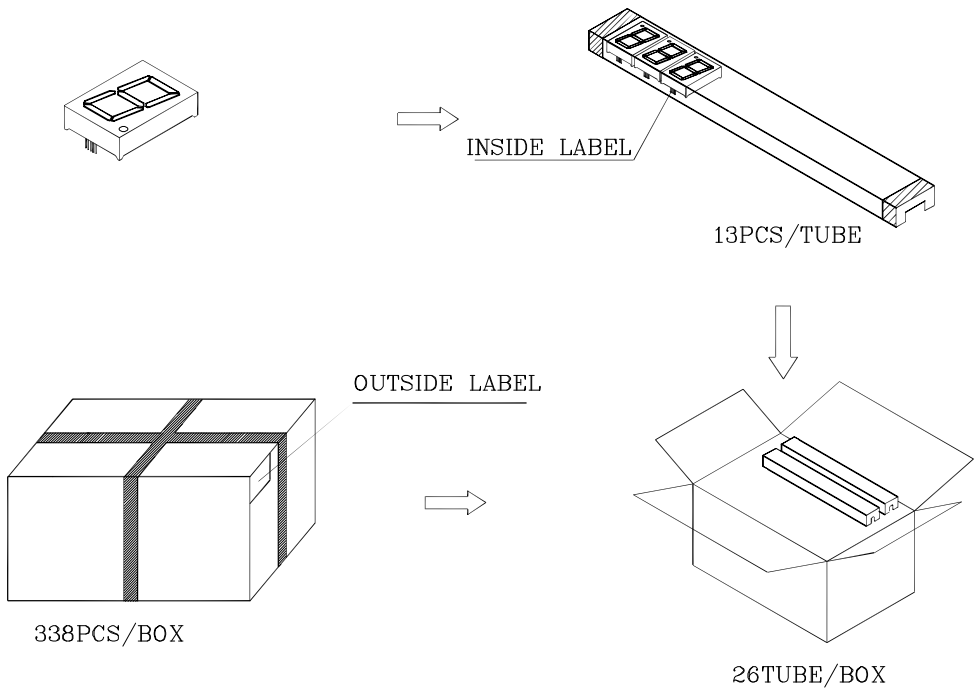
If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

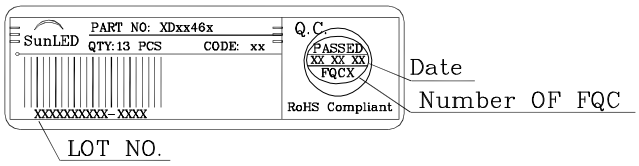
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

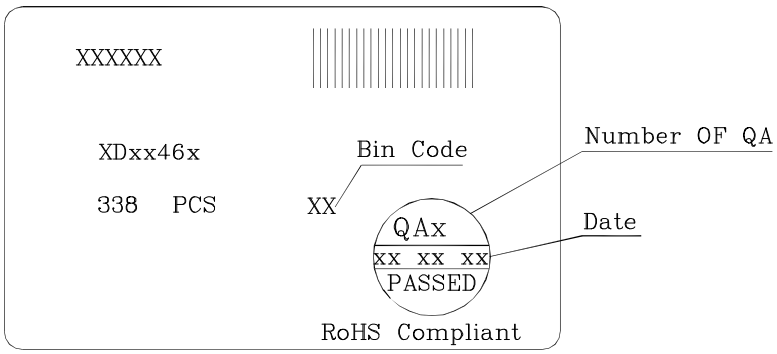
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



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